

ABSTRACT

The present invention discloses an electroplating apparatus, comprising a membrane frame and an ion-exchange membrane. The ion-exchange membrane is disposed at the bottom of the membrane frame. The membrane frame includes a plurality of first spray holes for discharging cathode liquid. The liquid outlet direction of the plurality of first spray holes forms a first predetermined angle with the vertically downward direction, and the first predetermined angle is an acute angle. The cathode liquid discharged from the first spray holes flows downward to flush the ion-exchange membrane, promotes the fluidity of the flow field in the lower layer of a cathode chamber, reduces crystalline precipitation, and prevents the continuous increase of the resistance between an anode and a substrate of the electroplating apparatus, which would otherwise lead to an increase in the voltage between the anode and the substrate.